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Title

CAPACITOR DC-LINK ARRANGEMENT

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Short presentation

The present invention provides a capacitor DC-link arrangement, in particular for high current ripple applications. The capacitor DC-link arrangement comprises a substrate such as a PCB-based substrate, a first terminal and a second terminal which are both arranged on the substrate, a plurality of ceramic capacitor elements, wherein: each of the ceramic capacitor elements is connected as well to the first terminal and the second terminal, the plurality of ceramic capacitor elements are connected in parallel, and the ceramic capacitor elements are arranged and connected in a similar current path and in particular in the same resistance current path.

Applicability

The patent can be applied on every electronic circuit that needs a high capacitance filtering and high current ripples.

Images

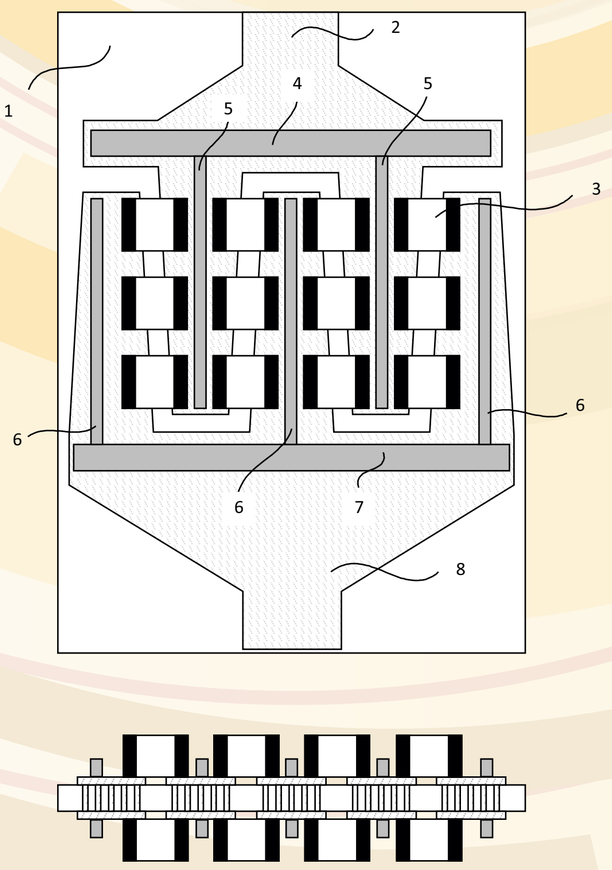

Fig. 1. Model 1

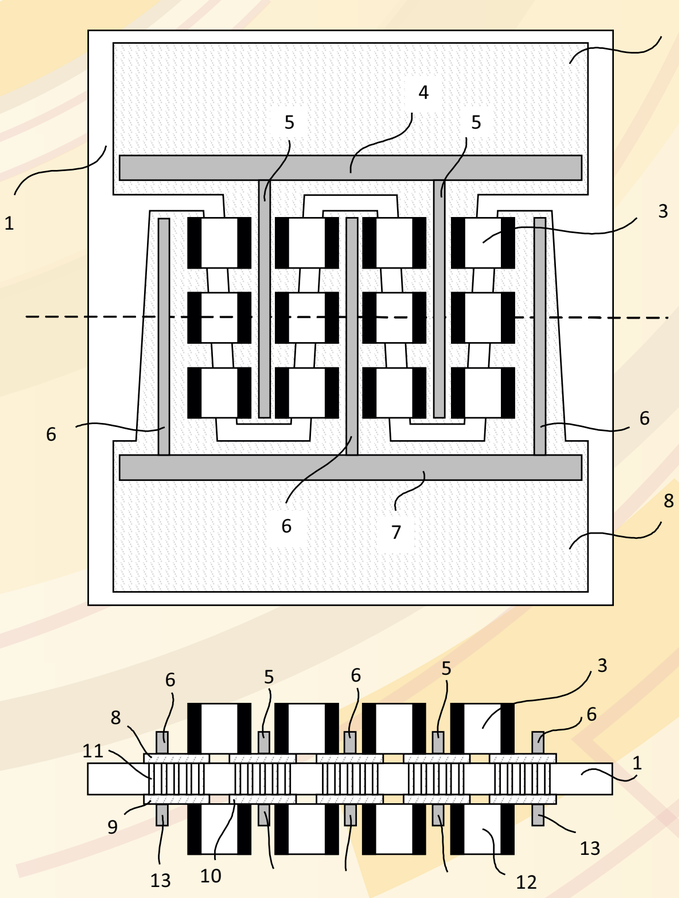

Fig. 2. Model 2

1 - PCB material

2 - Positive top copper layer

3 - ML-Ceramic capacitors – top layer

4 - Straitening horizontal bar- positive top layer

5 - Straitening vertical bars – positive top layer

6 - Straitening vertical bars – negative top layer

7 - Straitening horizontal bar- negative top layer

8 - Negative top copper layer

9 - Negative bottom copper layer

10 - Positive bottom copper layer

11 - PCB through hole via

12 - ML-Ceramic capacitors – bottom layer

13 - Straitening vertical bars – negative bottom layer

14 - Straitening vertical bars – positive bottom layer